

PHOTONICS PACKAGING METHOD

ABSTRACT

A photonics packaging method is provided. The photonics packaging method includes providing a substrate (10) and attaching a first optical device (12) to the substrate (10). The first optical device (12) includes a first mode converter (14) optically coupled to a first integrated photonics chip (16). A second optical device (32) is also attached to the substrate (10). The second optical device (32) includes a second mode converter (34) optically coupled to a second integrated photonics chip (36). The second optical device (32) is of a greater height than the first optical device (12). An index-matching material (56) is disposed in a space between the first and second optical devices (12) and (32) and a force is applied on the second optical device (32) to cause the second optical mode converter (34) to align with the first optical mode converter (14). The index-matching material (56) is subsequently cured.

[FIG. 1A]